ELECTRICAL CHARACTERISTICS (@ 25°C unless otherwise specified)

	Symbol	1N5802	1N5804	1N5806	Unit
Average forward current max. (pcb mounted; T_A = 55°C)					
for sine wave	$I_{F(AV)}$	←	1.3	→	A
for square wave (d = 0.5)	$I_{F(AV)}$	←	1.4	→	A
Average forward current max. (T_L = 55°C; L = 3/8")					
for sine wave	$I_{F(AV)}$	←	3.1	→	A
for square wave	$I_{F(AV)}$	←	3.3	→	A
I^2t for fusing (t = 8.3mS) max.	I^2t	←	10.0	→	A^2S
Forward voltage drop max. @ I_F = 1.0A, T_j = 25°C	V_F	←	0.875	→	V
Reverse current max.					
@ V_{RWM}, T_j = 25°C	I_R	←	1.0	→	µA
@ V_{RWM}, T_j = 100°C	I_R	←	50	→	µA
Reverse recovery time max. 1.0A I_F to 1.0A I_R. Recovers to 0.1A I_{RR}.	t_{rr}	←	25	→	nS
Junction capacitance typ. @ V_R = 5V , f = 1MHz	C_j	←	25	→	ρF

THERMAL CHARACTERISTICS

	Symbol	1N5802	1N5804	1N5806	Unit
Thermal resistance - junction to lead Lead length = 0.75"	$R_{\theta JL}$	←	36	→	°C/W
Thermal resistance - junction to amb. on 0.06" thick pcb. 1 oz. copper.	$R_{\theta JA}$	←	100	→	°C/W

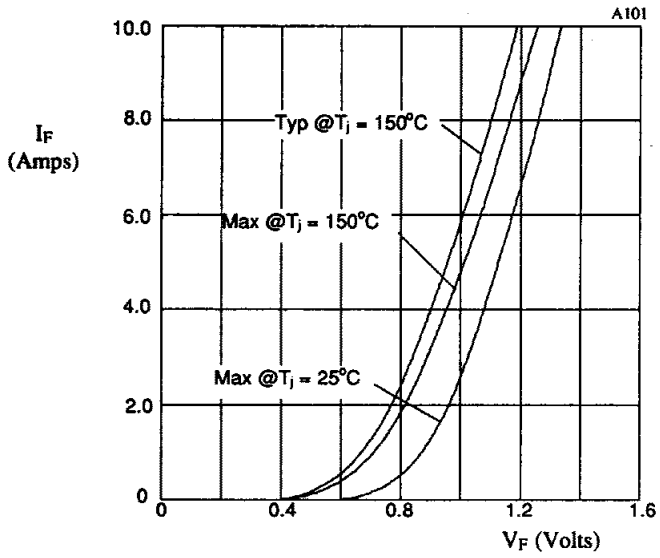

Fig 1. Forward voltage drop as a function of forward current.

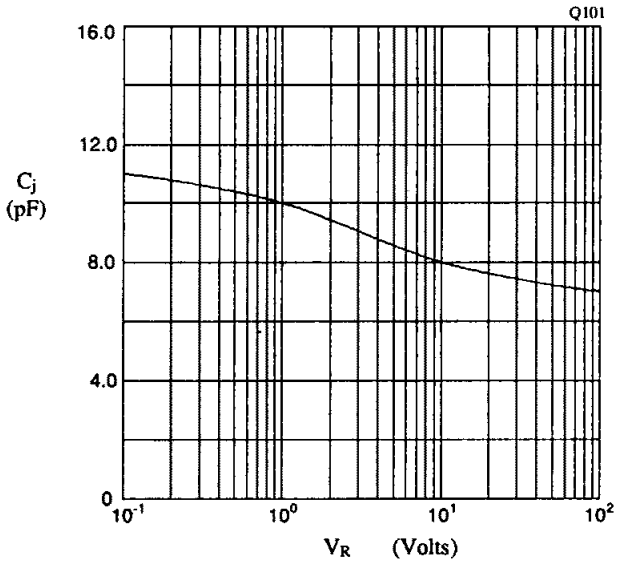

Fig 2. Typical junction capacitance as a function of reverse voltage.